User.1

NOTES

1. 4 layer PCB
2. PCB Thickness: 1.6 mm
3. Solder mask color: GREEN
4. Material: FR4-TG155
5. Surface Finish: HASL (with lead)
6. Outer Copper Weight: 1 oz
7. Inner Copper Weight: 0.5 oz
8. Impedance Control: NO
9. Via Covering: Plugged
10. Minimum Via Size/Hole Diameter: 0.89 mm/ 0.508 mm
11. Board Outline Tolerance: +/-0.2 mm

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6000 mm
Board overall dimensions:	108.0598 mm x 78.9830 mm		
Min track/spacing:	0.3048 mm / 0.2499 mm	Min hole diameter:	0.0000 mm
Copper Finish:	HAL SnPb	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Drill Map:

- × 0.508mm / 0.0200'' (62 holes)
- ○ 0.508mm / 0.0200'' (2 holes)
- + 1.020mm / 0.0402'' (40 holes)
- □ 1.067mm / 0.0420'' (8 holes)
- ◇ 2.700mm / 0.1063'' (3 holes)
- ⊠ 1.500mm / 0.0591'' (6 holes) (not plated)
- ✳ 1.800mm / 0.0709'' (2 holes) (not plated)
- ⊠ 3.400mm / 0.1339'' (8 holes) (not plated)

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	White	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	prepreg	FR4	3.93701 mils	Not specified	4.5	0.02
In1.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	48.8189 mils	Not specified	4.5	0.02
In2.Cu	copper		1.37795 mils		1	0
Dielectric	prepreg	FR4	3.93701 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	White	1	0